

VERSION WITH MARKINGS TO SHOW CHANGES MADESPECIFICATION:

Specification at page 1, line 10:

In recent years, surface acoustic wave filters have been widely used in mobile communication devices. Surface acoustic wave filters of a longitudinal mode type or a ladder type are used as a filter in a ~~radiofrequency~~radio frequency (RF) stage. With the improvement in performance of communication devices such as portable telephones, there has been an increasing demand for reducing the loss and increasing the attenuation in surface acoustic wave filters.

Specification at page 5, line 10:

~~The 1st invention~~One aspect of the present invention is a surface acoustic wave filter comprising:

Specification at page 5, line 20:

~~The 2nd invention~~Another aspect of the present invention is the surface acoustic wave filter ~~according to 1st invention~~, wherein the pitch of electrode fingers of the IDT electrode larger in number of electrode fingers in said input and output IDT electrode is larger than the pitch of electrode fingers smaller in number of electrode fingers.

Specification at page 6, line 3:

~~The 3rd invention~~Still another aspect of the present invention is a surface acoustic wave filter comprising:

Specification at page 6, line 13:

~~The 4th invention~~ Yet still another aspect of the present invention is the surface acoustic wave filter ~~according to 1st invention~~, wherein the metalization ratio of an IDT electrode larger in number of electrode fingers in said input and output IDT electrodes is lower than the metalization ratio of an IDT electrode smaller in number of electrode fingers.

Specification page 6, line 19:

~~The 5th invention~~ Still yet another aspect of the present invention is the surface acoustic wave filter ~~according to any one of 1st to 4th inventions~~, wherein if an IDT electrode has a plurality of electrode finger pitches, the pitch of main excitation electrode fingers is set as a basic pitch.

Specification at page 6, line 24:

~~The 6th invention~~ A further aspect of the present invention is the surface acoustic wave filter ~~according to any one of 1st to 4th inventions~~, wherein a peak frequency of a radiation characteristic of said input IDT electrode is substantially equal to a peak frequency of a radiation characteristic of said output IDT electrode.

Specification at page 7, line 5:

~~The 7th invention~~ A still further aspect of the present invention is the surface acoustic wave filter ~~according to 6th invention~~, wherein one of said input IDT electrode and said output IDT electrode comprises a first IDT electrode including a pair of electrode fingers opposed to each other;

Specification at page 7, line 24:

~~The 8th invention~~ A yet further aspect of the present invention is the surface acoustic wave filter ~~according to 6th invention~~, wherein one of said input IDT

electrode and said output IDT electrode comprises first, fourth, and fifth IDT electrodes each including a pair of electrode fingers opposed to each other;

Specification at page 8, line 24:

~~The 9th invention~~ A still yet further aspect of the present invention is the surface acoustic wave filter ~~according to 6th invention~~, wherein the film thickness of said first IDT electrode and the film thickness of each of said second and third IDT electrodes are different from each other.

Specification at page 9, line 4:

~~The 10th invention~~ An additional aspect of the present invention is the surface acoustic wave filter ~~according to 6th invention~~, wherein the material of said first IDT electrode and the material of each of said second and third IDT electrodes are different from each other.

Specification at page 9, line 9:

~~The 11th invention~~ A still additional aspect of the present invention is the surface acoustic wave filter ~~according to 7th invention~~, wherein the metalization ratio of said first IDT electrode and the metalization ratio of each of said second and third IDT electrodes are equal to each other;

Specification at page 9, line 12:

~~The 12th invention~~ A yet additional aspect of the present invention is the surface acoustic wave filter ~~according to 7th invention~~, wherein the metalization ratio of said first IDT electrode, the metalization ratio of said second IDT electrode and the metalization ratio of said third IDT electrode are different from each other.

Specification at page 10, line 1:

~~The 13th invention~~ A still yet additional aspect of the present invention is the surface acoustic wave filter ~~according to 7th invention~~, wherein a plurality of filter tracks each having first, second, and third IDT electrodes, and first and second reflector electrodes are formed on said piezoelectric substrate, and said plurality of filter tracks function as one filter in cooperation with each other.

Specification at page 10, line 8:

~~The 14th invention~~ A supplementary aspect of the present invention is the surface acoustic wave filter ~~according to 13th invention~~, wherein each of said plurality of filter tracks is identical in configuration to the others.

Specification at page 10, line 12:

~~The 15th invention~~ A still supplementary aspect of the present invention is the surface acoustic wave filter ~~according to 13th invention~~, wherein at least one of said plurality of filter tracks is different in configuration from the others.

Specification at page 10, line 16:

~~The 16th invention~~ A yet supplementary aspect of the present invention is the surface acoustic wave filter ~~according to 7th invention~~, further comprising a first reflector electrode placed on the opposite side of said second IDT electrode on said piezoelectric substrate opposite from the side on which said first IDT electrode are placed; and

Specification at page 11, line 4:

~~The 17th invention~~ A still yet supplementary aspect of the present invention is a method of manufacturing a surface acoustic wave filter, comprising

Specification at page 11, line 14:

~~The 18th invention~~ Another aspect of the present invention is a communication device comprising:

a transmitting circuit which outputs a transmitted wave; and

a receiving circuit to which a wave to be received is input,

wherein a surface acoustic wave filter ~~according to 1st invention~~ is used in said transmitting circuit and/or in said receiving circuit.

Specification at page 11, line 23:

~~The 19th invention~~ Still another aspect of the present invention is a communication device comprising:

a transmitting circuit which outputs a transmitted wave; and

a receiving circuit to which a wave to be received is input,

wherein the surface acoustic wave filter ~~according to 3rd invention~~ is used in said transmitting circuit and/or in said receiving circuit.